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GARLICK HARRISON & MARKISON LLP			HOANG, ANN THI	
P.O. BOX 160727			ART UNIT	PAPER NUMBER
AUSTIN, TX 78716-0727			2836	

DATE MAILED: 05/16/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

<b>Office Action Summary</b>	<b>Application No.</b>	<b>Applicant(s)</b>	
	10/645,027	KHORRAM, SHAHLA	
	<b>Examiner</b>	<b>Art Unit</b>	
	Ann T. Hoang	2836	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --  
**Period for Reply**

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

#### **Status**

1) Responsive to communication(s) filed on 22 February 2006.  
 2a) This action is **FINAL**.                    2b) This action is non-final.  
 3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

#### **Disposition of Claims**

4) Claim(s) 1-20 is/are pending in the application.  
 4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.  
 5) Claim(s) \_\_\_\_\_ is/are allowed.  
 6) Claim(s) 1-20 is/are rejected.  
 7) Claim(s) \_\_\_\_\_ is/are objected to.  
 8) Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

#### **Application Papers**

9) The specification is objected to by the Examiner.  
 10) The drawing(s) filed on 12 January 2004 is/are: a) accepted or b) objected to by the Examiner.  
 Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  
 Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).  
 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

#### **Priority under 35 U.S.C. § 119**

12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).  
 a) All    b) Some \* c) None of:  
 1. Certified copies of the priority documents have been received.  
 2. Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.  
 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

#### **Attachment(s)**

1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892)	4) <input type="checkbox"/> Interview Summary (PTO-413)
2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948)	Paper No(s)/Mail Date. _____
3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date _____	5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152)
	6) <input type="checkbox"/> Other: _____

## DETAILED ACTION

### ***Specification***

1. The objections related to the disclosure have been withdrawn due to the amendments to the specification.

### ***Claim Objections***

2. The claim objections regarding informalities have been withdrawn due to amendments to the claims.

### ***Claim Rejections - 35 USC § 103***

3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

4. Claims 1-20 are rejected under 35 U.S.C. 103(a) as being unpatentable over Woo et al. (US 6,445,039) in view of Kluge et al. (US 2003/0183403) and Tsuji (US 5,901,023).

Regarding claim 1, Woo et al. discloses a radio frequency integrated circuit (RFIC) having sectional electrostatic discharge (ESD) protection, the RFIC comprising: an analog receive section 3402 operably coupled to convert inbound radio frequency (RF) signals 3410 into inbound low intermediate frequency (IF) signals 3412, and a

digital section 3416 operably coupled to convert the inbound low IF signals 3412 into inbound digital baseband signals 3414. Fig. 34 and column 39, lines 40-45 describe these elements with their numerical references. Woo et al. discloses in column 39, lines 57-63 that the RFIC may also contain an analog transmit section, which would be operably coupled to convert outbound low IF signals into outbound RF signals, to compliment analog receive section 3402, thereby making the RFIC a transceiver system. A transceiver 5818 is depicted in Fig. 58. For two-way transmission, digital section 3416 would necessarily convert outbound digital baseband signals into the outbound low IF signals as well. See column 58, lines 42-52 and column 61, lines 62-67. Woo et al. discloses RFIC sections (6102, 6104, 6106) to have localized ground connections (6110, 6112, 6114) as well as localized ESD protection circuitry 6108, with each local ESD protection circuit operably coupled to its respective local ground connection. See Fig. 61; column 2, lines 3-9; column 63, lines 14-19 and 60-67; and line 64, lines 1-18. Thus, it is understood that analog receive section 3402 has an analog receive ground connection, wherein analog receive section 3402 includes analog receive ESD protection circuitry operably coupled to the analog receive ground connection; that the analog transmit section has an analog transmit ground connection, wherein the analog transmit section includes analog transmit ESD protection circuitry operably coupled to the analog transmit ground connection; and that digital section 3416 has a digital ground connection. Woo et al. discloses parasitic capacitance to be a problem of concern when different RFIC sections are placed on separate power and ground lines, but does not disclose a first inductor assembly operably coupling the

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analog receive ground connection to the digital ground connection or a second inductor assembly operably coupling the analog transmit ground connection to the digital ground connection.

However, Kluge et al. discloses a parasitic capacitance 206 formed between an input terminal 203 and a ground terminal 204 in an RFIC having ESD protection, as well as the method of inserting an inductor 205 between the terminals in order to form a resonance tank with parasitic capacitance 206. See Fig. 2a and page 3, paragraph 26. It would have been obvious to one of ordinary skill in the art at the time of the invention to combine the method of inserting an inductor between two terminals having a parasitic capacitance in between, as taught by Kluge et al., with the RFIC of Woo et al. in order to form resonance circuits between the analog receive ground connection and the digital ground connection, as well as between the analog transmit ground connection and the digital ground connection. The resonance tank would be designed to have a resonant frequency in accordance with operating radio frequency of the integrated circuit. Specifically, the inductance value would be chosen so that, under normal operation (high frequencies) of the RFIC, the inductor would act as an open circuit and compensate for the parasitic capacitance. During ESD events (low frequencies), the inductor would act as a short, tying the grounds together to provide a common shunt for the ESD.

The combination above provides ESD protection between the analog receive ground and digital ground connections, as well as between the analog transmit ground and digital ground connections, since Woo et al. discloses the problem of parasitic

capacitance between separate power and ground lines, and the inductive resonance tanks of Kluge et al. would remedy this problem by being placed across all separate power and ground lines. Neither of these references specifies the intention of providing this type of ESD protection between analog and digital domains.

However, Tsuji discloses a desire to provide ESD protection circuitry between analog (11) and digital (14, 15) domains of an IC in order to reduce the effects of noise that analog domains receive from digital domains. Furthermore, Tsuji discloses connecting the ESD protection across analog ground and digital ground connections. See Figs. 1, 4 and 5; column 1, lines 67-68; column 2, lines 1-3 and 20-25; and column 3, lines 16-17 and 32-36. It would have been obvious to one of ordinary skill in the art at the time of the invention to use the inductors of Kluge et al. in the RFIC of Woo et al. in order to provide ESD protection between analog and digital domains, as clearly motivated by Tsuji.

Regarding claim 2, Woo et al. discloses the desire to fabricate all blocks of the transceiver on a single die, as partitioning more and more functionality into a single integrated circuit chip allows for considerable savings in component parts costs. See column 17, lines 59-62. This entails fabricating the analog receive section, the analog transmit section, and the digital section on a single die. Kluge et al. discloses fabricating the components of the RFIC on a single die, but that, in an application involving relatively large sized inductors, inductor 3 can be manufactured off-chip. See page 4, paragraph 37. It would have been obvious to one of ordinary skill in the art at the time of the invention to manufacture the first and second inductor assemblies off-

chip with respect to the single die in order to not add the bulk of large inductors to the single die.

Regarding claim 3, Kluge et al. discloses that inductor 3 may be packaged within the same package housing the single die. See page 4, paragraph 37. It would have been obvious to one of ordinary skill in the art at the time of the invention to package the first and second inductor assemblies within the same package housing the single die in order to contain the RFIC in a single package.

Regarding claim 4, Woo et al. discloses multiple RFIC sections (6102, 6104, 6106). These sections are labeled for the purpose of an example drawing, the function of each unspecified, and it is understood that any number of RFIC sections may be utilized. See Fig. 61 and column 64, lines 16-18. Woo et al. shows RFIC sections (6102, 6104, 6106) to each have a second ESD protection circuit operably coupled to a localized power source connection (6110, 6112, 6114). The multiple RFIC sections (6102, 6104, 6106) are interpreted to include analog receive section 3402, the analog transmit section, and digital section 3416. Thus, analog receive section 3402 includes second analog receive ESD protection circuitry operably coupled to an analog receive power source connection; the analog transmit section includes second analog transmit ESD protection circuitry operably coupled to an analog transmit power source connection; and digital 3416 section includes a digital power source connection. Woo et al. does not disclose a third inductor assembly operably coupling the analog receive power source connection to the digital power source connection for ESD protection between analog and digital domains, or a fourth inductor assembly operably coupling

the analog transmit power source connection to the digital power source connection for ESD protection between analog and digital domains.

However, Kluge et al. discloses the method of inserting an inductor 205 between two terminals 203 and 204 to form a resonance tank with a parasitic capacitance 206 existing between the terminals. It would have been obvious to one of ordinary skill in the art at the time of the invention to combine the method of inserting an inductor between two terminals having a parasitic capacitance in between, as taught by Kluge et al., with the RFIC of Woo et al. in order to form resonance circuits between the analog receive power source connections and the digital power source connections, as well as between the analog transmit power source connections and the digital power source connections.

Furthermore, Tsuji discloses a desire to provide ESD protection circuitry between analog (11) and digital (14, 15) domains of an IC by connecting the ESD protection across analog power and digital power connections. See Figs. 1 and 5; column 2, lines 20-25; and column 3, lines 32-36. It would have been obvious to one of ordinary skill in the art at the time of the invention to use the inductors of Kluge et al. in the RFIC of Woo et al. in order to provide ESD protection between analog and digital domains, as clearly motivated by Tsuji. See above rejection on claim 1.

Regarding claim 5, Woo et al. discloses a low noise amplifier 3502 operably coupled to amplify the inbound RF signals 3406 to produce amplifier inbound RF signals 3410; a mixing module 1916 operably coupled to mix amplified inbound RF signals 3410 with a receive local oscillation 1902 to produce down converted signals 1918; and

a receive filtering module 1912 operably coupled to filter down converted signals 1918 to produce inbound low IF signals 3412. The reference actually discloses a cascade of multiple mixers and filters which tune the received signal before signal processing circuitry splits the analog component off of the inbound low IF signal and outputs it in a digital format. From this, it is understood that the signal processing circuitry includes an analog to digital converter with an analog portion, as would be required for this type of splitting. See abstract; Figs. 19, 34, and 35; column 60, lines 66-67 and column 61, lines 1-7. Some of these components are shown as connecting to but not within the block that represents analog receive section 3402 in the drawings. However, it would be obvious to one of ordinary skill in the art at the time of the invention to diagram them as being a part of analog receive section 3402, as they perform the same functions regardless of their grouping in the drawings. Since Woo et al. discloses an unlimited number of RFIC sections (6102, 6104, 6106) to have localized ground connections (6110, 6112, 6114) (see Fig. 61), it is interpreted that low noise amplifier 3502, mixing module 1916, receive filtering module 1912, and the analog portion of the analog to digital converter constitute RFIC sections and that these RFIC sections each have a localized ground connection. Thus, low noise amplifier 3502 has a low noise amplifier ground connection, mixing module 1916 has a mixing module ground connection, receive filtering module 1912 has a receive filtering ground connection, and the analog portion has an analog portion ground connection. Woo et al. discloses parasitic capacitance to be a problem of concern when different RFIC sections are placed on

separate power and ground lines, but does not disclose any inductors operably coupling the aforementioned ground connections.

However, Kluge et al. discloses a parasitic capacitance 206 formed between and input terminal 203 and a ground terminal 204 in an RFIC having ESD protection, as well as the method of inserting an inductor 205 between the terminals in order to form a resonance tank with parasitic capacitance 206. See Fig. 2a and page 3, paragraph 26. It would have been obvious to one of ordinary skill in the art at the time of the invention to combine the method of inserting an inductor between two terminals having a parasitic capacitance in between, as taught by Kluge et al., with the RFIC of Woo et al. in order to form resonance circuits in the form of a first inductor operably coupling the low noise amplifier ground connection to the mixing module ground connection, a second inductor operably coupling the mixing module ground connection to the receive filtering ground connection, a third inductor operably coupling the receive filtering ground connection to the analog portion ground connection, and a fourth inductor operably coupling the analog portion ground connection to the digital ground connection. See above rejection on claim 1.

Regarding claim 6, Woo et al. discloses in column 39, lines 57-63 an analog transmit section with functionally equivalent circuitry as the analog receive section. It is understood that transceiver 5818, depicted in Fig. 58, comprises a power amplifier operably coupled to amplify up converted signals to produce the outbound RF signals, a mixing module operably coupled to mix filtered low IF signals with a transmit local oscillation to produce the up converted signals, a filtering module operably coupled to

filter the outbound low IF signals to produce the filtered low IF signals, and an analog portion of a digital to analog converter which converts digital outbound low IF signals into the outbound low IF signals, as these components would be the compliment of those in the analog receive section as described above. These components are interpreted to constitute some of the RFIC sections (6102, 6104, 6106) with localized ground connections (6110, 6112, 6114). Woo does not disclose any inductors operably coupling the aforementioned ground connections.

However, it would have been obvious to one of ordinary skill in the art at the time of the invention to combine the method of inserting an inductor between two terminals having a parasitic capacitance in between, as taught by Kluge et al., with the RFIC of Woo et al. in order to form resonance circuits between the localized ground connections. Claim 6 is rejected under the same reasoning as that of claim 5. See above rejection.

Regarding claim 7, Woo et al. discloses a low noise amplifier 3502 operably coupled to amplify inbound RF signals 3406 to produce amplifier inbound RF signals 3410 and an analog receive radio section (Fig. 19) operably coupled to convert amplified inbound RF signals 3410 into inbound low IF signals 3412. These sections are interpreted to constitute some of the RFIC sections (6102, 6104, 6106) with localized ground connections (6110, 6112, 6114). Some of these components are shown as connecting to but not within the block that represents analog receive section 3402 in the drawings. However, it would be obvious to one of ordinary skill in the art at the time of the invention to diagram them as being a part of analog receive section

3402, as they perform the same functions irregardless of their grouping in the drawings. Woo does not disclose any inductors operably coupling the aforementioned ground connections.

However, it would have been obvious to one of ordinary skill in the art at the time of the invention to combine the method of inserting an inductor between two terminals having a parasitic capacitance in between, as taught by Kluge et al., with the RFIC of Woo et al. in order to form resonance circuits between the localized ground connections. Claim 7 is rejected under the same reasoning as that of claim 5. See above rejection.

Regarding claim 8, transceiver 5818, depicted in Fig. 58, comprises a power amplifier operably coupled to amplify up converted signals to produce the outbound RF signals and an analog transmit radio section operably coupled to produce the up converted signals from the outbound low IF signals, as these components would be the compliment of those in the analog receive section as described above. These components are interpreted to constitute some of the RFIC sections (6102, 6104, 6106) with localized ground connections (6110, 6112, 6114). Woo does not disclose any inductors operably coupling the aforementioned ground connections.

However, it would have been obvious to one of ordinary skill in the art at the time of the invention to combine the method of inserting an inductor between two terminals having a parasitic capacitance in between, as taught by Kluge et al., with the RFIC of Woo et al. in order to form resonance circuits between the localized ground

connections. Claim 8 is rejected under the same reasoning as that of claim 6. See above rejection.

Regarding claim 9, Woo et al. discloses a radio frequency integrated circuit (RFIC) having sectional electrostatic discharge (ESD) protection, the RFIC comprising: an analog receive section 3402 operably coupled to convert inbound radio frequency (RF) signals 3410 into inbound low intermediate frequency (IF) signals 3412; a power amplifier operably coupled to amplify up converted signals to produce the outbound RF signals (see Fig. 58); an analog transmit radio section (see Fig. 58) operably coupled to produce the up converted signals from the outbound low IF signals, as this section would be the compliment of the analog receive section as described above; and a digital section 3416 operably coupled to convert inbound low IF signals 3412 into inbound digital baseband signals 3414 and to necessarily convert outbound digital baseband signals into the outbound low IF signals. See Fig. 34. These components are interpreted to constitute some of the RFIC sections (6102, 6104, 6106) with localized ground connections (6110, 6112, 6114). Woo et al. discloses RFIC sections (6102, 6104, 6106) to also include localized ESD protection circuitry 6108, with each local ESD protection circuit operably coupled to its respective local ground connection. See Fig. 61; column 2, lines 3-9; column 63, lines 14-19 and 60-67; and line 64, lines 1-18. Thus, it is understood that analog receive section 3402 has analog receive ESD protection circuitry 6108 operably coupled to the analog receive ground connection. Woo does not disclose any inductors operably coupling the aforementioned ground connections for ESD protection between analog and digital domains.

However, it would have been obvious to one of ordinary skill in the art at the time of the invention to combine the method of inserting an inductor between two terminals having a parasitic capacitance in between, as taught by Kluge et al., with the RFIC of Woo et al. in order to form resonance circuits between the localized ground connections.

Furthermore, Tsuji discloses a desire to provide ESD protection circuitry between analog (11) and digital (14, 15) domains of an IC by connecting the ESD protection across analog ground and digital ground connections. See Figs. 1, 4 and 5; column 1, lines 67-68; column 2, lines 1-3 and 20-25; and column 3, lines 16-17 and 32-36. It would have been obvious to one of ordinary skill in the art at the time of the invention to use the inductors of Kluge et al. in the RFIC of Woo et al. in order to provide ESD protection between analog and digital domains, as clearly motivated by Tsuji. Claim 9 is rejected under the same reasoning as that of claim 1. See above rejection.

Claim 10 is rejected under the same reasoning as that of claim 2. See above rejection.

Claim 11 is rejected under the same reasoning as that of claim 3. See above rejection.

Regarding claim 12, Woo et al. shows RFIC sections (6102, 6104, 6106) to each have a second ESD protection circuit operably coupled to a localized power source connection (6110, 6112, 6114). The multiple RFIC sections (6102, 6104, 6106) are interpreted to include analog receive section 3402, the power amplifier (see Fig. 58), and digital section 3416. Thus, analog receive section 3402 includes second analog

receive ESD protection circuitry operably coupled to an analog receive power source connection; the power amplifier includes second power amplifier ESD protection circuitry operably coupled to a power amplifier power source connection; and digital 3416 section includes a digital power source connection. Woo does not disclose any inductors operably coupling the aforementioned power source connections for ESD protection between analog and digital domains.

However, it would have been obvious to one of ordinary skill in the art at the time of the invention to combine the method of inserting an inductor between two terminals having a parasitic capacitance in between, as taught by Kluge et al., with the RFIC of Woo et al. in order to form resonance circuits between the localized power source connections.

Furthermore, Tsuji discloses a desire to provide ESD protection circuitry between analog (11) and digital (14, 15) domains of an IC by connecting the ESD protection across analog power and digital power connections. See Figs. 1 and 5; column 2, lines 20-25; and column 3, lines 32-36. It would have been obvious to one of ordinary skill in the art at the time of the invention to use the inductors of Kluge et al. in the RFIC of Woo et al. in order to provide ESD protection between analog and digital domains, as clearly motivated by Tsuji. Claim 12 is rejected under the same reasoning as that of claim 4. See above rejection.

Claim 13 is rejected under the same reasoning as that of claim 5. See above rejection.

Claim 14 is rejected under the same reasoning as that of claim 6. See above rejection. The “analog transmit radio section” of claim 9 is understood to be essentially the same as the “analog transmit section” of claim 1.

Claim 15 is rejected under the same reasoning as that of claim 7. See above rejection.

Regarding claim 16, Woo et al. discloses a radio frequency integrated circuit (RFIC) having sectional electrostatic discharge (ESD) protection, the RFIC comprising: a power amplifier operably coupled to amplify up converted signals to produce the outbound RF signals, an analog radio section 5818 operably coupled to convert inbound RF signals 3506 into inbound low IF signals 3412 and operably coupled to produce the up converted signals from outbound low IF signals, and a digital section 3416 operably coupled to convert inbound low IF signals 3412 into inbound digital baseband signals 3414 and to convert outbound digital baseband signals into the outbound low IF signals. See Figs. 34, 35, and 58; column 58, lines 42-52 and column 61, lines 62-67. These sections are interpreted to constitute some of the RFIC sections (6102, 6104, 6106) with localized ground connections (6110, 6112, 6114) and localized ESD protection circuitry 6108, with each local ESD protection circuit operably coupled to its respective local ground connection. See Fig. 61. Woo does not disclose any inductors operably coupling the aforementioned ground connections for ESD protection between analog and digital domains.

However, it would have been obvious to one of ordinary skill in the art at the time of the invention to combine the method of inserting an inductor between two terminals

having a parasitic capacitance in between, as taught by Kluge et al., with the RFIC of Woo et al. in order to form resonance circuits between the localized ground connections.

Furthermore, Tsuji discloses a desire to provide ESD protection circuitry between analog (11) and digital (14, 15) domains of an IC by connecting the ESD protection across analog ground and digital ground connections. See Figs. 1, 4 and 5; column 1, lines 67-68; column 2, lines 1-3 and 20-25; and column 3, lines 16-17 and 32-36. It would have been obvious to one of ordinary skill in the art at the time of the invention to use the inductors of Kluge et al. in the RFIC of Woo et al. in order to provide ESD protection between analog and digital domains, as clearly motivated by Tsuji. Claim 16 is rejected under the same reasoning as that of claim 1. See above rejection.

Claim 17 is rejected under the same reasoning as that of claim 2. See above rejection.

Claim 18 is rejected under the same reasoning as that of claim 3. See above rejection.

Claim 19 is rejected under the same reasoning as that of claim 12. See above rejection. The “analog radio section” of claim 19 is understood to be a two-way transceiver equivalent of the “analog receive section” of claim 12.

Regarding claim 20, Woo et al. discloses analog radio section 5818 to comprise: a low noise amplifier 3502 operably coupled to amplify inbound RF signals 3406 to produce amplifier inbound RF signals 3410, a receive mixing module 1916 operably coupled to mix amplified inbound RF signals 3410 with a receive local oscillation 1902

to produce down converted signals 1918, and a receive filtering module 1912 operably coupled to filter down converted signals 1918 to produce inbound low IF signals 3412. It is understood that the signal processing circuitry includes an ADC analog portion of an analog to digital converter, as would be required for splitting the analog component off of the inbound low IF signal and outputting it in a digital format. See above rejection on claim 5. Since Woo et al. discloses analog radio section 5818 to contain an analog transmit section to compliment analog receive section 3402, it is understood that analog radio section 5818 also comprises: a transmit mixing module operably coupled to mix filtered low IF signals with a transmit local oscillation to produce the up converted signals; a transmit filtering module operably coupled to filter the outbound low IF signals to produce the filtered low IF signals; and a DAC analog portion of a digital to analog converter, wherein the digital to analog converter converts digital outbound low IF signals into the outbound low IF signals, as these components would be the compliment of those in the analog receive section as described above. These components are interpreted to constitute some of the RFIC sections (6102, 6104, 6106) with localized ground connections (6110, 6112, 6114). Woo does not disclose any inductors operably coupling the aforementioned ground connections.

However, it would have been obvious to one of ordinary skill in the art at the time of the invention to combine the method of inserting an inductor between two terminals having a parasitic capacitance in between, as taught by Kluge et al., with the RFIC of Woo et al. in order to form resonance circuits between the localized ground

connections. Claim 20 is rejected under the same reasoning as that of claim 1. See above rejection.

***Response to Arguments***

5. Applicant's arguments with respect to claims 1-20 have been considered but are moot in view of the new ground(s) of rejection.

***Conclusion***

6. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Ann T. Hoang, whose telephone number is 571-272-

2724. The examiner can normally be reached Monday through Friday, 8:00 a.m. to 5:00 p.m.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Brian Sircus, can be reached at 571-272-2058. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

ATH  
3 May 2006



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